

What is claimed is:

1. An integrated circuit device module, in which a plurality of groups of integrated circuit devices are mounted on a motherboard, comprising:

5 a plurality of branched signal lines, formed on said motherboard and extending from a common branch node to individual distal ends, along which a common signal is supplied to said groups of integrated circuit devices respectively,

10 wherein each of said plurality of branched signal lines comprises a first branched signal line having a first length from said branch node to the distal end, and a second branched signal line having a second length from said branch node to the distal end which is shorter than said first length, and an inductance generated by the unit length of said first branched signal line is smaller than an inductance generated by the unit length of said second branched signal line.

15 20 2. An integrated circuit device module according to claim 1, wherein said first branched signal line is wider than said second branched signal line.

25 20 25 3. An integrated circuit device module according to claim 1, wherein said motherboard has a power wiring layer formed through an insulating film at a position opposite said branched signal lines, and an area of said power wiring layer opposite said first

branched signal line is greater, by the unit length, than that opposite said second branched signal line.

4. An integrated circuit device module according to claim 1, wherein said motherboard has a power wiring layer formed through an insulating film at a position opposite said branched signal lines, and an area of said power wiring layer opposite to said second branched signal line is removed.

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10 5. An integrated circuit device module according to claim 1, wherein at least one part of said second branched signal line is formed of a material containing nickel or another ferromagnetic material.

15 6. An integrated circuit device module according to one of claims 1 to 5, wherein a drive device for outputting said common signal is mounted on said motherboard, and said drive device outputs said common signal to said common node.

20 7. An integrated circuit device module, in which a plurality of groups of integrated circuit devices are mounted on a motherboard, comprising:

25 a plurality of branched signal lines, formed on said motherboard and extending from a common branch node to individual distal ends, along which a common signal is supplied to said groups of integrated circuit devices respectively,

wherein each of said plurality of branched signal lines comprises a first branched signal line

having a first length from said branch node to the distal end, and a second branched signal line having a length from said branch node to the distal end which is shorter than said first length, and distal ends of said first and said second branched signal line are connected together to form a signal line loop.

8. An integrated circuit device module according to claim 7, further comprising:

10 a plurality of signal line loops, each having substantially the same length.

9. An integrated circuit device module according to claim 7 or 8, wherein a drive device for outputting said common signal is mounted on said motherboard, and said drive device outputs said common signal to said common node.

10. An integrated circuit device module, in which a plurality of integrated circuit devices are mounted on a motherboard, comprising:

20 first and second branched signal lines, formed on said motherboard and each extending from a common branch node to a distal end, through which a common signal is supplied to said integrated circuit devices respectively,

25 wherein said first branched signal line having a first length from said common branch node to its distal end, and said second branched signal line having a second length from said common branch node to

its distal end which is shorter than said first length,  
and an inductance per unit length of said first  
branched signal line is smaller than that of said  
second branched signal line.